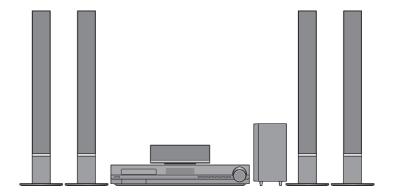


MODEL: HI



# DVD/CD RECEIVER SERVICE MANUAL



**MODEL: HT552TH** 

SH52TH-C, SH52TH-S,

SH52TH-W

U LO

P/NO : AFN31640733 DECEMBER, 2006

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• SERVICING PRECAUTIONS
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• PRINTED CIRCUIT DIARGAMS
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SECTION 5. SPEAKER PART
SECTION 6. REPLACEMENT PARTS LIST

# **SECTION 1. GENERAL**

# SERVICING PRECAUTIONS NOTES REGARDING HANDLING OF THE PICK-UP

#### 1. Notes for transport and storage

- 1) The pick-up should always be left in its conductive bag until immediately prior to use.
- 2) The pick-up should never be subjected to external pressure or impact.

Storage in conductive bag





Drop impact

#### 2. Repair notes

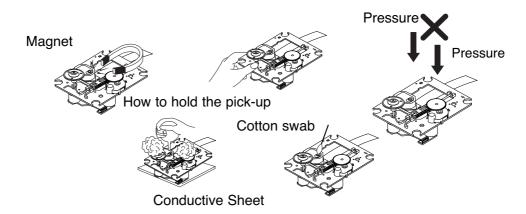
- 1) The pick-up incorporates a strong magnet, and so should never be brought close to magnetic materials.
- 2) The pick-up should always be handled correctly and carefully, taking care to avoid external pressure and impact. If it is subjected to strong pressure or impact, the result may be an operational malfunction and/or damage to the printed-circuit board.
- 3) Each and every pick-up is already individually adjusted to a high degree of precision, and for that reason the adjustment point and installation screws should absolutely never be touched.
- 4) Laser beams may damage the eyes! Absolutely never permit laser beams to enter the eyes! Also NEVER switch ON the power to the laser output part (lens, etc.) of the pick-up if it is damaged.



NEVER look directly at the laser beam, and don't let contact fingers or other exposed skin.

#### 5) Cleaning the lens surface

If there is dust on the lens surface, the dust should be cleaned away by using an air bush (such as used for camera lens). The lens is held by a delicate spring. When cleaning the lens surface, therefore, a cotton swab should be used, taking care not to distort this.



6) Never attempt to disassemble the pick-up.

Spring by excess pressure. If the lens is extremely dirty, apply isopropyl alcohol to the cotton swab. (Do not use any other liquid cleaners, because they will damage the lens.) Take care not to use too much of this alcohol on the swab, and do not allow the alcohol to get inside the pick-up.

#### NOTES REGARDING COMPACT DISC PLAYER REPAIRS

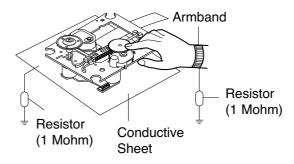
#### 1. Preparations

- 1) Compact disc players incorporate a great many ICs as well as the pick-up (laser diode). These components are sensitive to, and easily affected by, static electricity. If such static electricity is high voltage, components can be damaged, and for that reason components should be handled with care.
- 2) The pick-up is composed of many optical components and other high-precision components. Care must be taken, therefore, to avoid repair or storage where the temperature of humidity is high, where strong magnetism is present, or where there is excessive dust.

#### 2. Notes for repair

- 1) Before replacing a component part, first disconnect the power supply lead wire from the unit
- 2) All equipment, measuring instruments and tools must be grounded.
- 3) The workbench should be covered with a conductive sheet and grounded.

  When removing the laser pick-up from its conductive bag, do not place the pick-up on the bag. (This is because there is the possibility of damage by static electricity.)
- 4) To prevent AC leakage, the metal part of the soldering iron should be grounded.
- 5) Workers should be grounded by an armband (1M  $\Omega$ )
- 6) Care should be taken not to permit the laser pick-up to come in contact with clothing, in order to prevent static electricity changes in the clothing to escape from the armband.
- 7) The laser beam from the pick-up should NEVER be directly facing the eyes or bare skin.



#### **ESD PRECAUTIONS**

## **Electrostatically Sensitive Devices (ESD)**

Some semiconductor (solid state) devices can be damaged easily by static electricity. Such components commonly are called Electrostatically Sensitive Devices (ESD). Examples of typical ESD devices are integrated circuits and some field-effect transistors and semiconductor chip components. The following techniques should be used to help reduce the incidence of component damage caused by static electricity.

- 1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any electrostatic charge on your body by touching a known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device, which should be removed for potential shock reasons prior to applying power to the unit under test.
- 2. After removing an electrical assembly equipped with ESD devices, place the assembly on a conductive surface such as aluminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
- 3. Use only a grounded-tip soldering iron to solder or unsolder ESD devices.
- 4. Use only an anti-static solder removal device. Some solder removal devices not classified as "anti-static" can generate electrical charges sufficient to damage ESD devices.
- 5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ESD devices.
- 6. Do not remove a replacement ESD device from its protective package until immediately before you are ready to install it. (Most replacement ESD devices are packaged with leads electrically shorted together by conductive foam, aluminum foil or comparable conductive materials).
- 7. Immediately before removing the protective material from the leads of a replacement ESD device, touch the protective material to the chassis or circuit assembly into which the device will by installed.

# CAUTION: BE SURE NO POWER IS APPLIED TO THE CHASSIS OR CIRCUIT, AND OBSERVE ALL OTHER SAFETY PRECAUTIONS.

8. Minimize bodily motions when handing unpackaged replacement ESD devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity sufficient to damage an ESD device).

#### **CAUTION. GRAPHIC SYMBOLS**

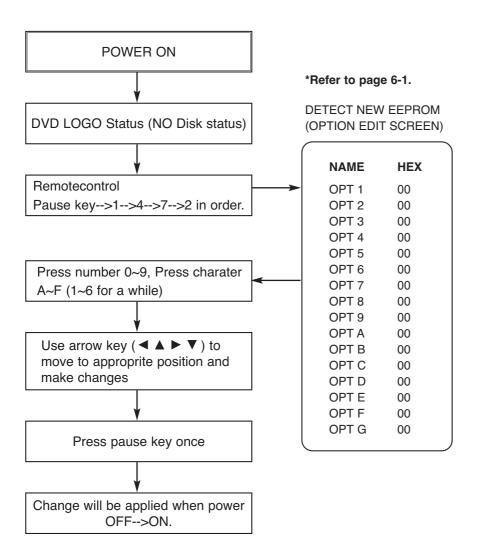


THE LIGHTNING FLASH WITH APROWHEAD SYMBOL. WITHIN AN EQUILATERAL TRIANGLE, IS INTENDED TO ALERT THE SERVICE PERSONNEL TO THE PRESENCE OF UNINSULATED "DANGEROUS VOLTAGE" THAT MAY BE OF SUFFICIENT MAGNITUDE TO CONSTITUTE A RISK OF ELECTRIC SHOCK.

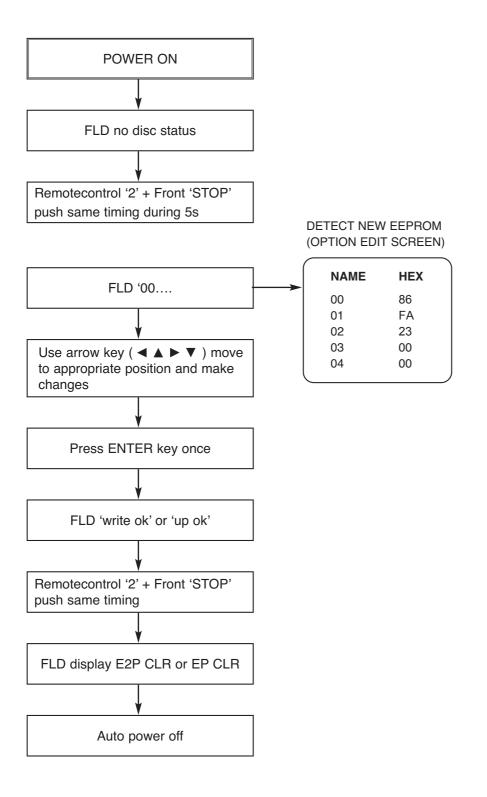


THE EXCLAMATION POINT WITHIN AN EQUILATERAL TRIANGLE IS INTENDED TO ALERT THE SERVICE PERSONNEL TO THE PRESENCE OF IMPORTANT SAFETY INFORMATION IN SERVICE LITERATURE.

# SERVICE INFORMATION FOR EEPROM(DVD PART)



# **SERVICE INFORMATION FOR EEPROM (AMP PART)**



#### **SPECIFICATIONS**

**GENERAL** 

Power supply Refer to main label.

Power consumption Refer to main label.

Net Weight 3.6 kg

External dimensions (W x H x D) 430 x 70 x 311 mm

Operating conditions Temperature: 5°C to 35°C, Operation status: Horizontal

Operating humidity 5% to 85%

Laser Semiconductor laser, wavelength 650 nm

CD/DVD

Signal system PAL 625/50, NTSC 525/60

Frequency response (audio) 200 Hz to 18 kHz

Signal-to-noise ratio (audio) More than 75 dB (1 kHz, NOP -6 dB, 20 kHz LPF/A-Filter)

Dynamic range (audio) More than 70 dB

Harmonic distortion (audio) 0.5 % (1 kHz, at 1W position) (20 kHz LPF)

**VIDEO** 

Video input 1.0 V (p-p), 75 Ω, negative sync., RCA jack x 1

Video output 1.0 V (p-p), 75 Ω, negative sync., RCA jack x 1/ SCART (TO TV)

COMPONENT VIDEO OUT (Y) 1.0 V (p-p), 75 ohms, negative sync, RCA jack x 1

(PB)/(PR) 0.7 V (p-p), 75 ohms, RCA jack x 1

**TUNER** 

FΜ

Tuning Range 87.5 - 108.0 MHz or 65.0 - 74.0 MHz, 87.5 - 108.0 MHz

Intermediate Frequency 10.7 MHz
Signal-to Noise Ratio 60 dB (Mono)
Frequency Response 140 - 8,000 Hz

AM [MW]

Tuning Range 522 - 1,620 kHz or 520 - 1,720 kHz

Intermediate Frequency 450 kHz

**AMPLIFIER** 

Stereo mode 70 W + 70 W ( $4\Omega$  at 1 kHz, THD 10 %) Surround mode Front: 70 W + 70 W (THD 10 %)

(\* Depending on the sound mode Center\*: 70 W

settings and the source, there may be no sound output.) Surround\*: 70 W + 70 W ( $4\Omega$  at 1 kHz, THD 10 %) Subwoofer\*: 150 W ( $3\Omega$  at 30 Hz, THD 10 %)

Inputs AUDIO IN, OPTICAL IN

Outputs MONITOR OUT, EURO AV (TO TV) OUT

COMPONENT VIDEO OUT

**SPEAKERS** 

Front/Rear Speaker Center speaker Passive Subwoofer (SH52TH-S) (SH52TH-C) (SH52TH-W)

Type 2 Way 3 Speaker 2 Way 3 Speaker 1 Way 1 Speaker 1 May 1 Speaker 3  $\Omega$ 

 Frequency Response
 100 - 20000 Hz
 150 - 20000 Hz
 40 - 1500 Hz

 Sound Pressure Level
 82 dB/W (1m)
 82 dB/W (1m)
 80 dB/W (1m)

 Rated Input Power
 70 W
 70 W
 150 W

Max. Input Power 140 W 140 W 300 W

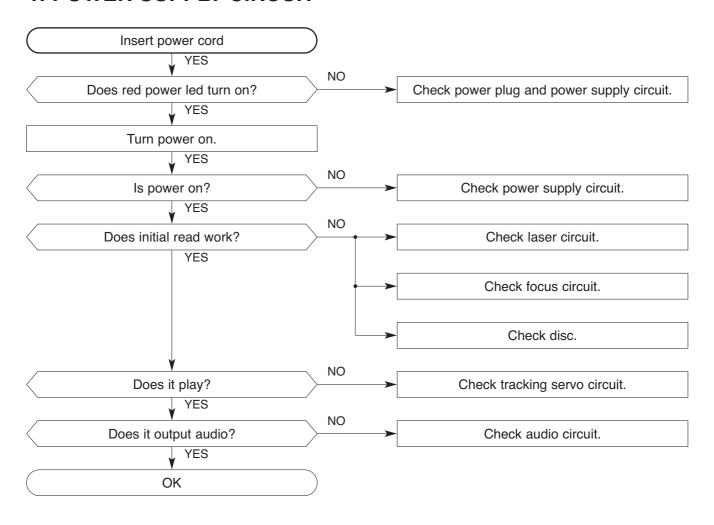
Net Dimensions (W x H x D) 260 x 1100 x 260 mm 330 x 86 x 121 mm 212 x 395 x 341 mm

Net Weight 3.0 kg 1.15 kg 6.0 kg

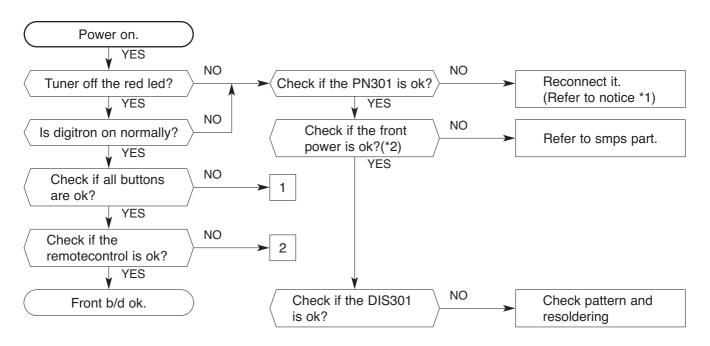
# **SECTION 2. AUDIO PART**

# **AUDIO TROUBLESHOOTING GUIDE**

#### 1. POWER SUPPLY CIRCUIT



# 2. FRONT CIRCUIT (1/2)

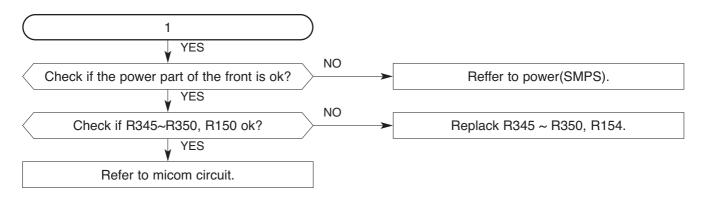


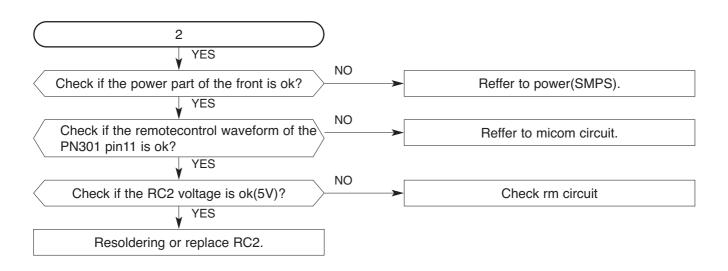
\*1 : When it is needed to reconnected FFC cable into PN301 Short 1pin of PN103 with 18pin of CN901 in amp part

\*2: PN603 Pins.

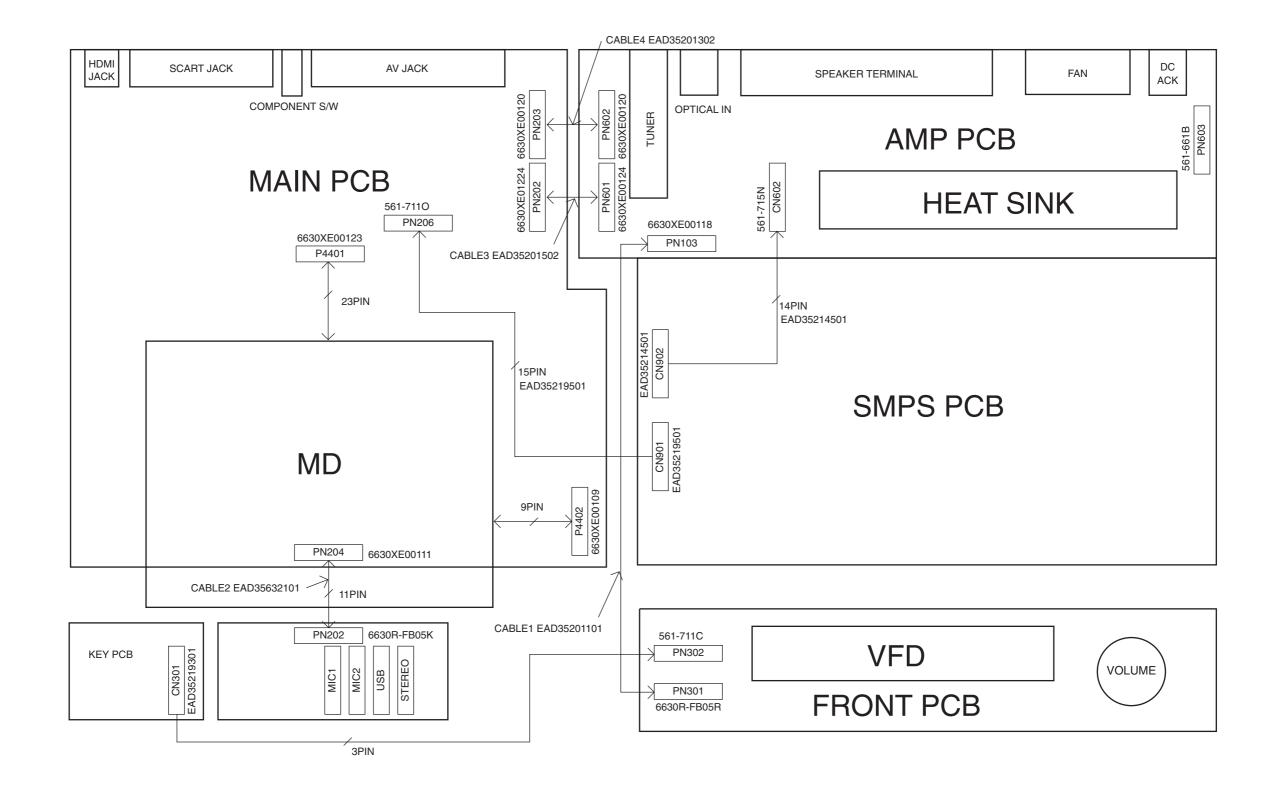
PIN1 : -35 VKK PIN2 : -30 FL+ PIN3 : -33 FL-PIN7 : +5V PIN13 : +5VA

# 3. FRONT CIRCUIT (2/2)

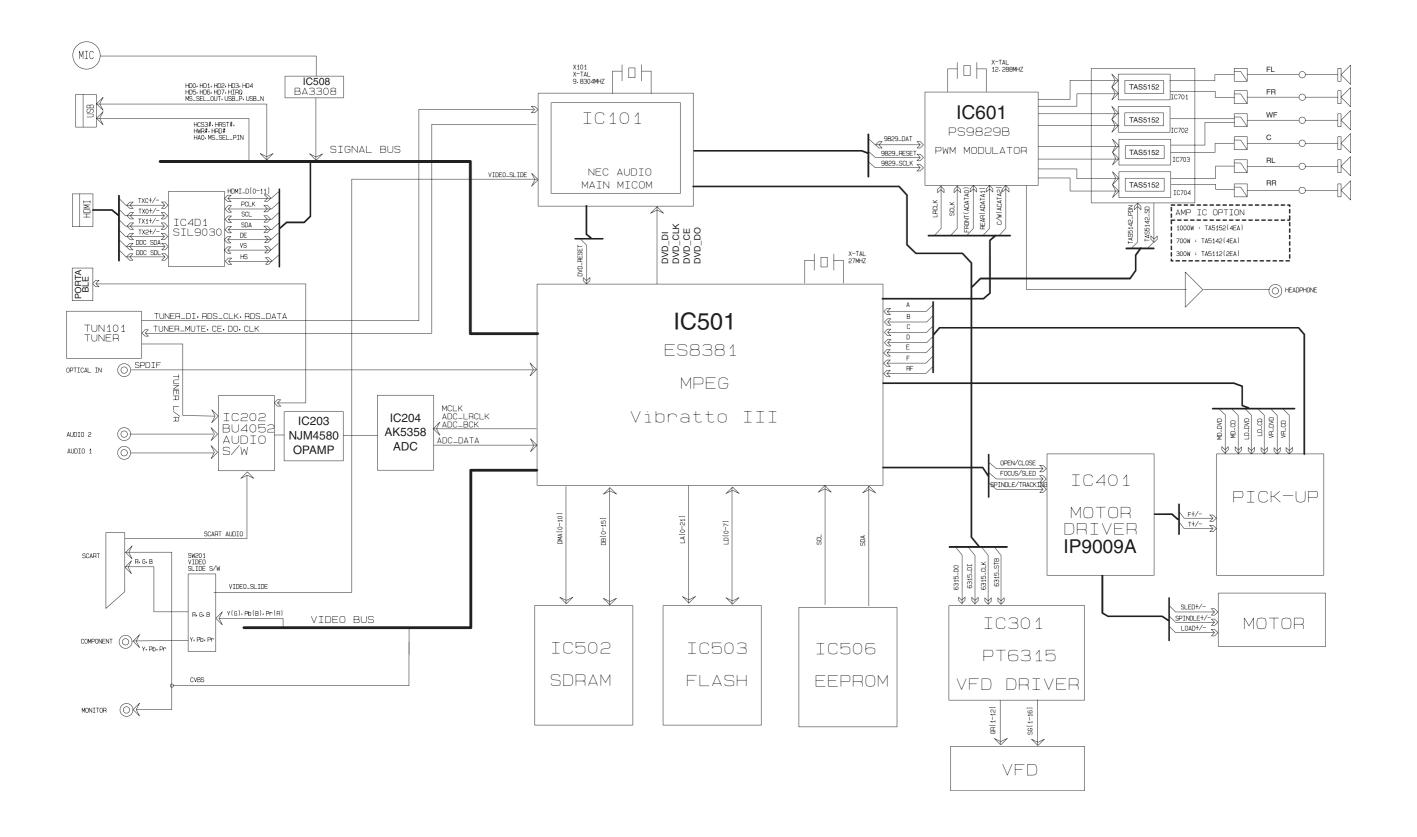




## **WIRING DIAGRAM**



## **BLOCK DIAGRAM**



#### **CIRCUIT DIAGRAMS**

#### 1. SMPS(POWER) CIRCUIT DIAGRAM

#### IMPORTANT SAFETY NOTICE

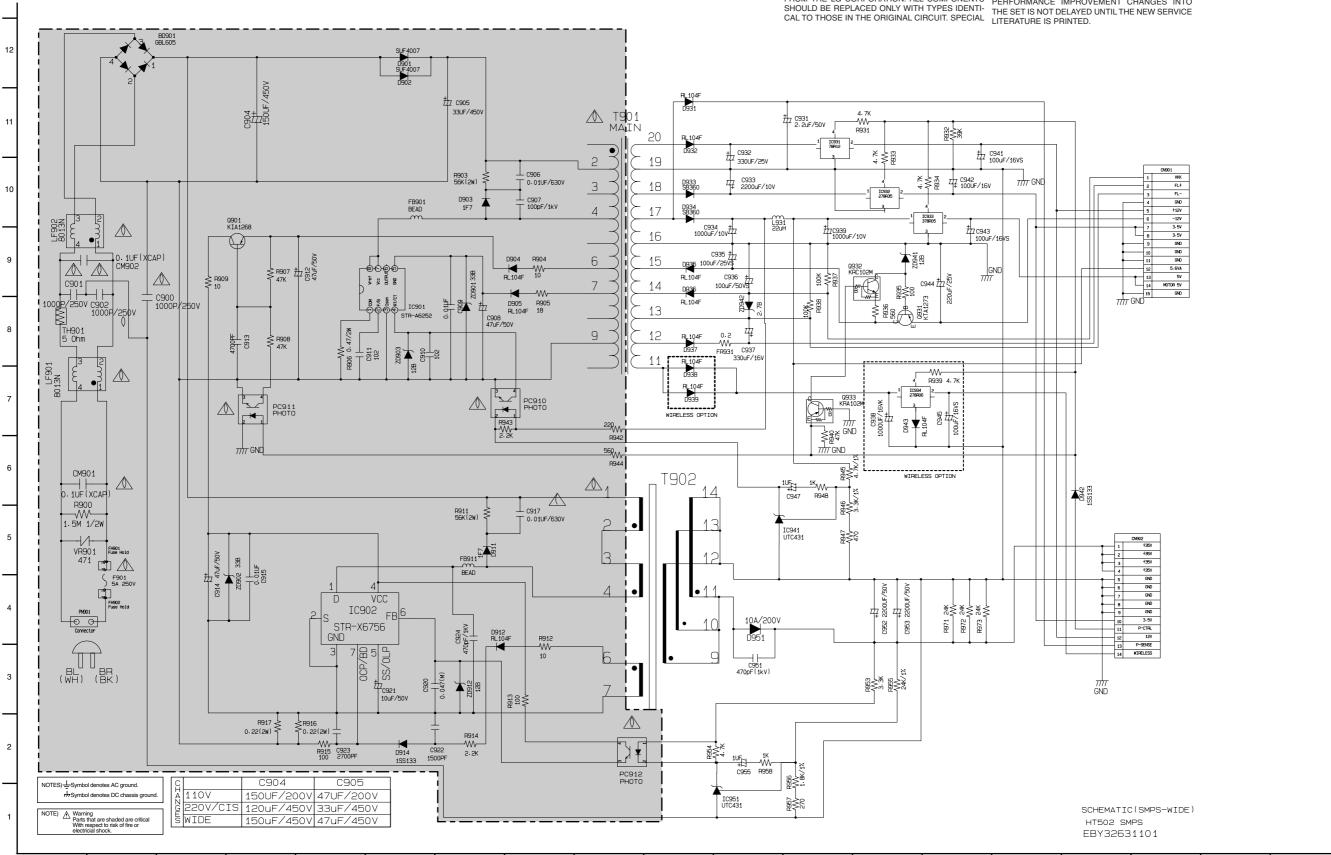
WHEN SERVICING THIS CHASSIS, UNDER NO CIR-WHEN SERVICING THIS CHASSIS, UNDER NO CIR-CUMSTANCES SHOULD THE ORIGINAL DESIGN BE MODIFIED OR ALTERED WITHOUT PERMISSION MODIFIED OR ALTERED WITHOUT PERMISSION MPLEMENTATION OF THE LATEST SAFETY AND

COMPONENTS ARE SHADED ON THE SCHEMATIC NOTE: FOR EASY IDENTIFICATION.

FROM THE LG CORPORATION. ALL COMPONENTS
PERFORMANCE IMPROVEMENT CHANGES INTO

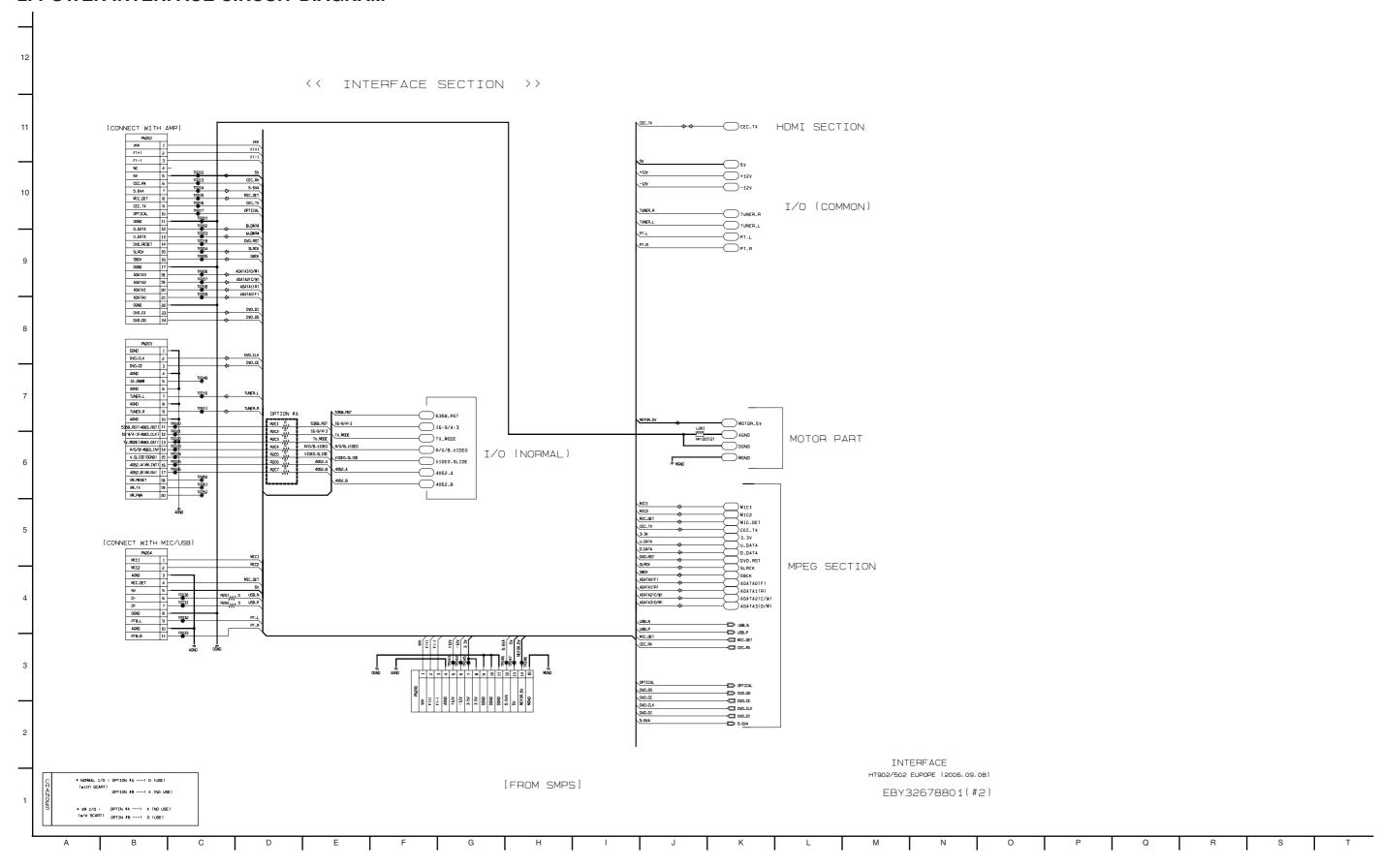
- Shaded(■) parts are critical for safety. Replace only
- with specified part number.

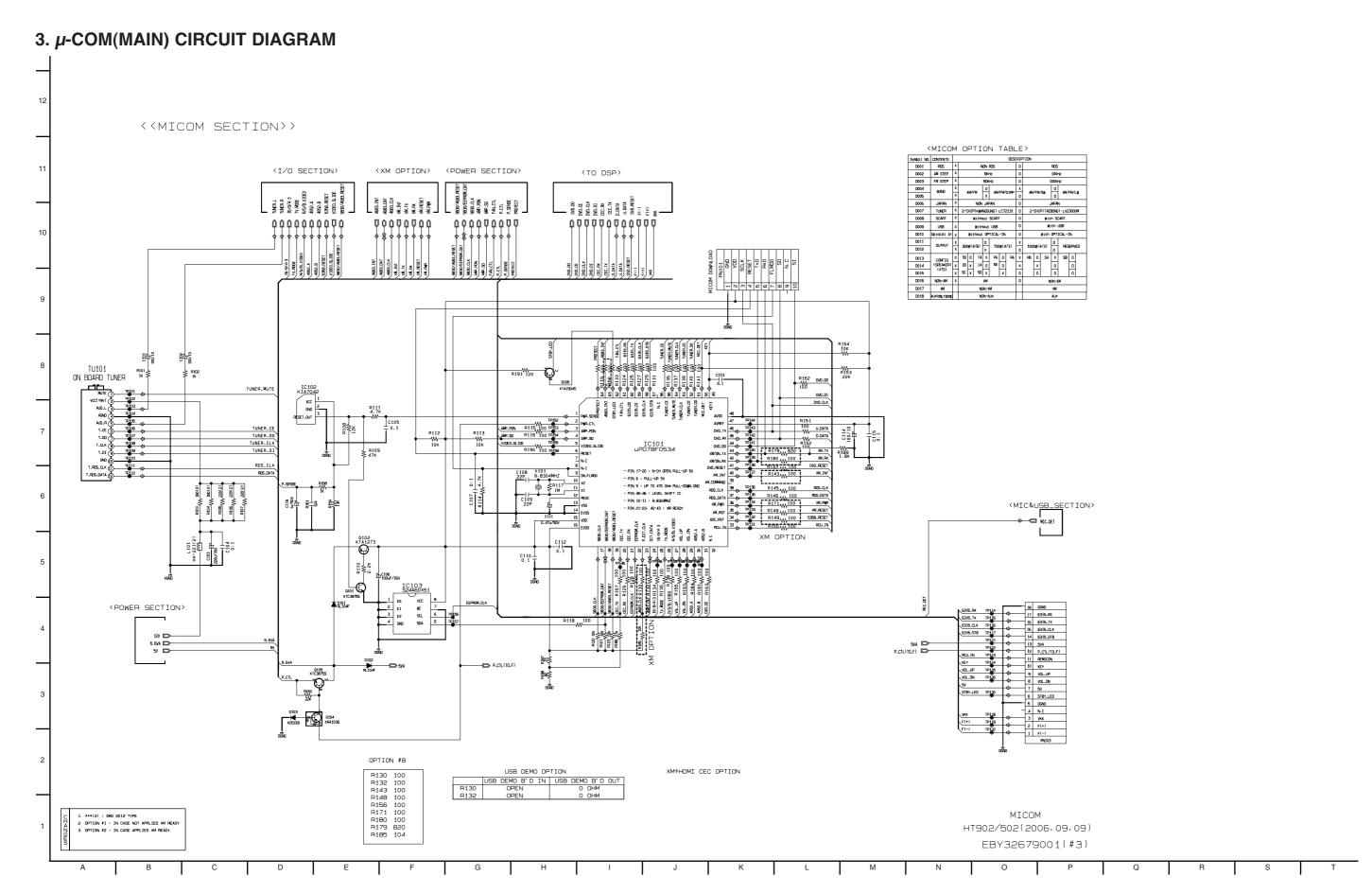
  2. Voltages are DC-measured with a digital voltmeter during Play mode.



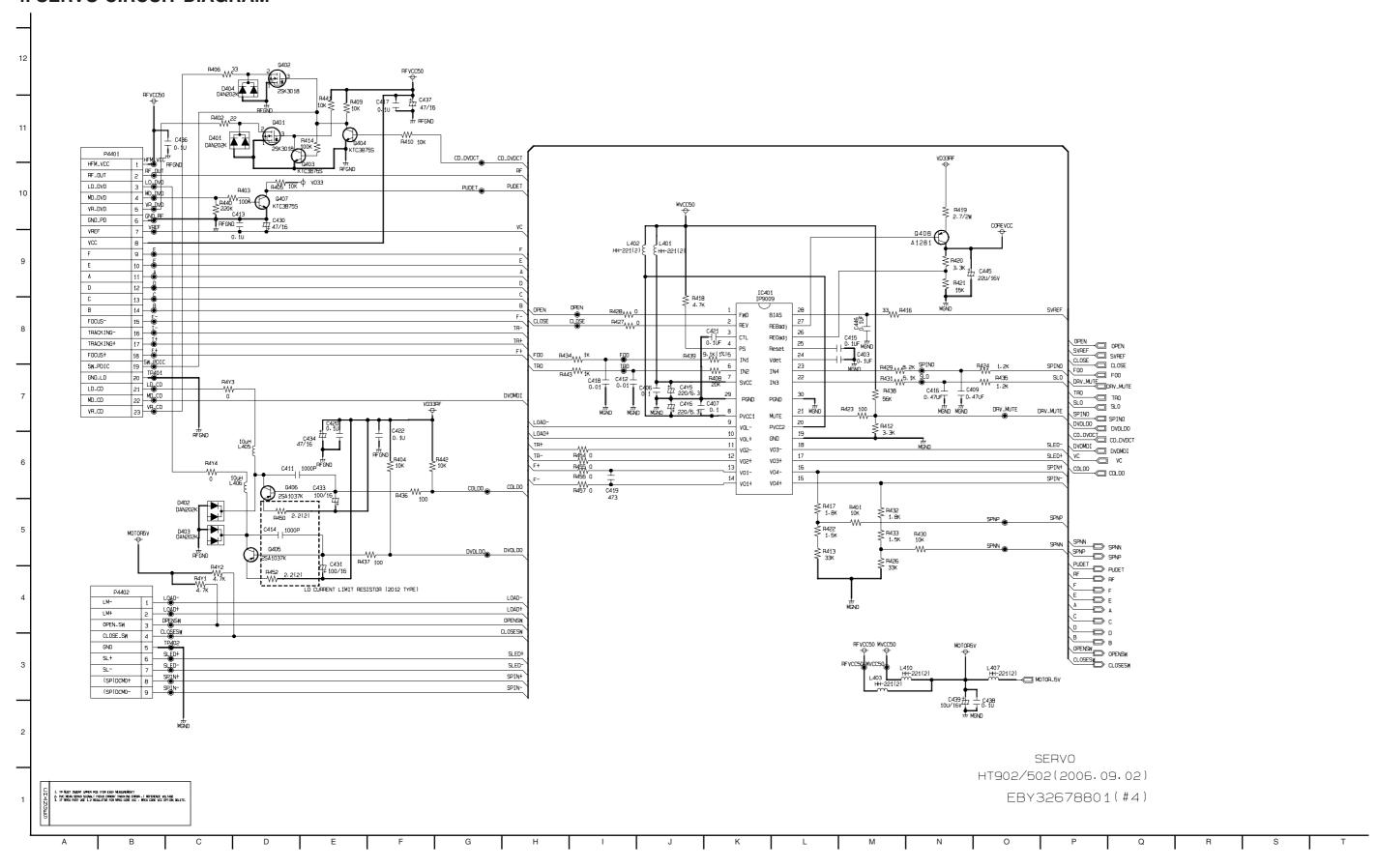
2-8

#### 2. POWER INTERFACE CIRCUIT DIAGRAM



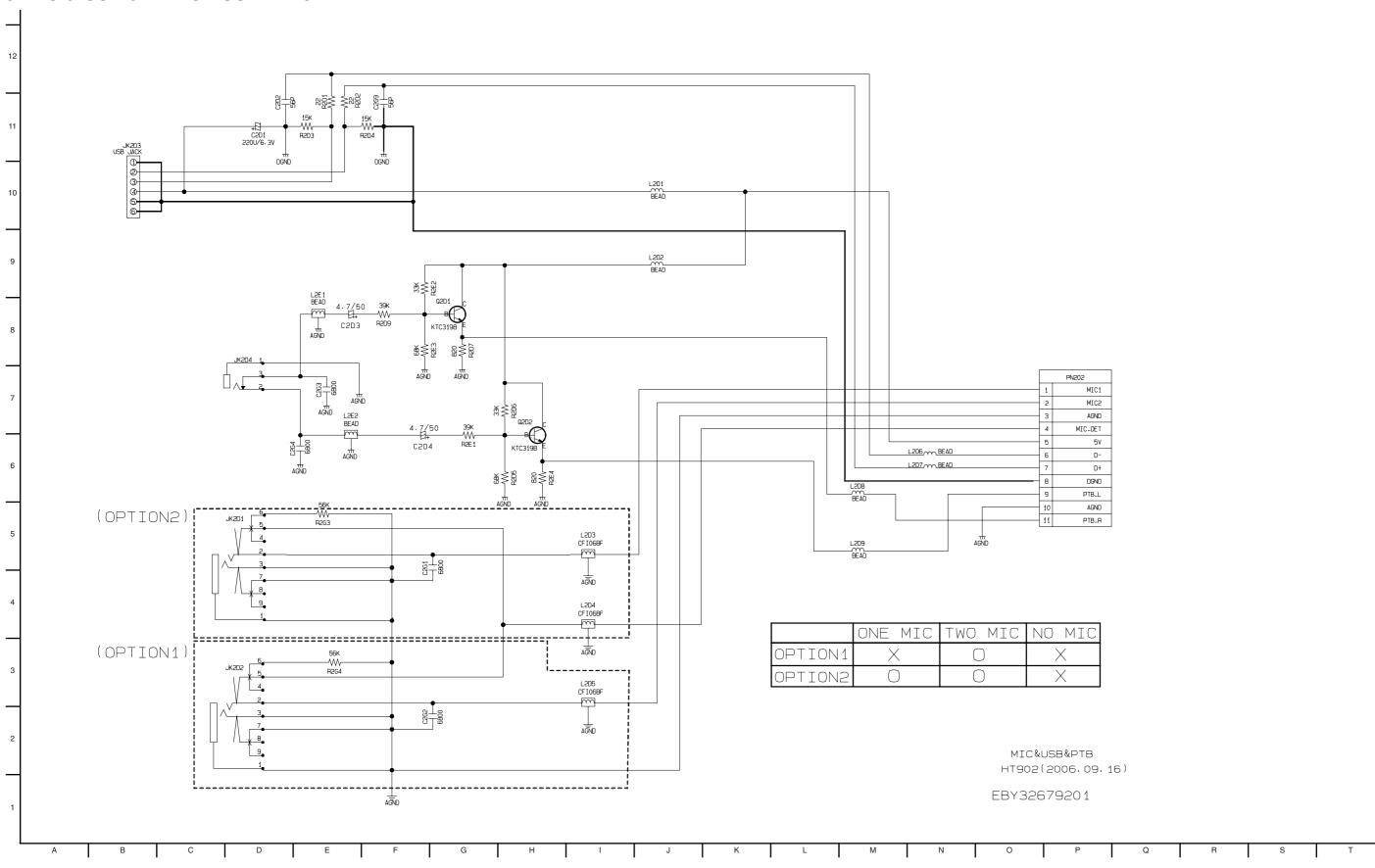


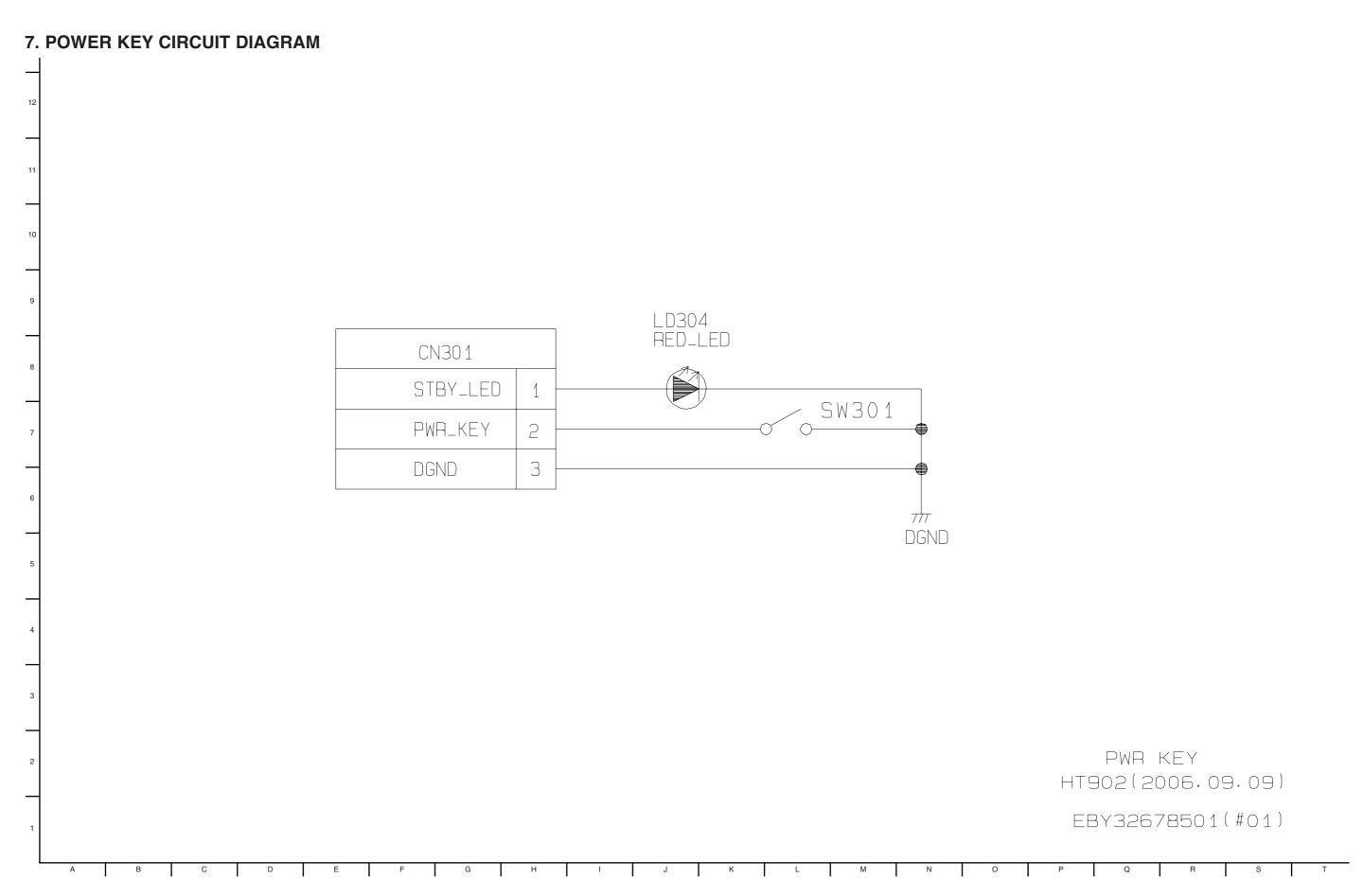
#### 4. SERVO CIRCUIT DIAGRAM



#### 5. I/O CIRCUIT DIAGRAM <<I/o SECTION>> OPTION #A OPTION #A TO DSP —**□** \$00u1 - ■ MCLK - □ LRCK DVD -COMPOSITE **─**□ Y/G **□** PB/B OPTION #A OPTION #A RGB/COMPONENT AUDIO\_IN\_R TUNER\_R TUNER\_L GND GND PT\_R AUDIO\_IN\_L - 5358\_RST BLUE 16:9/4:3 SCART\_CTL TV\_MODE GND N- C R/G/B\_VIDEO VIDEO-SLIDE GREEN GND GND RED GND GND OPTION #A V\_OUT V\_IN GND I/O HT902/502 EUPOPE (2006.09.08) EBY32678801(#3) \* xM I/O : OPTIN #A ---> x (NO USE)

#### 6. MIC & USB & PTB CIRCUIT DIAGRAM



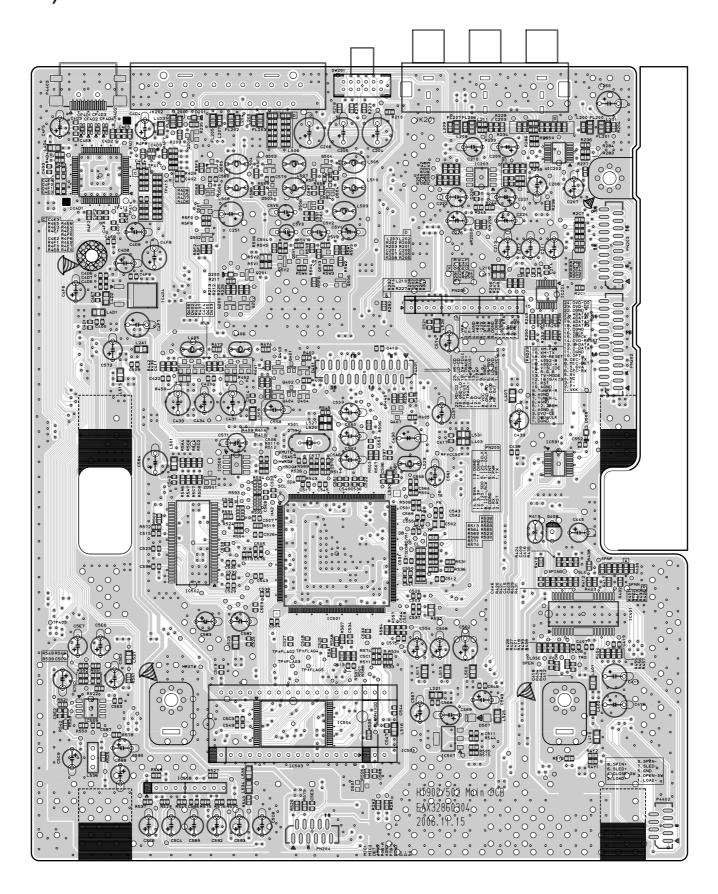


## 8. TIMER CIRCUIT DIAGRAM Symbol NO. CONTENTS D001 RDS D002 AM STEP 0. fuF AMP TO FRONT 6315\_RX 17 6315\_TX 6315\_CLK C322 | 100P(XXX) 4 | LED4 | SSC | DOUT 6315\_CLK 15 IC301 6315\_STB 14 5VA 13 P\_CTL 12 R362 1K \_\_\_\_\_\_ PT6315 KEY 10 VOL\_UP VOL\_DN VOL\_LP 9 VOL\_DN 8 DGND 5 N-C 4 3) KEY SWBCIL NO. LH-19696 SWBOI STANLBY SWBOI STANLBY SWBOI SWBOI-FARROH-FRESETSWBOI SWBOI SWBOI-FARROH-FRESETSWBOI SWBOI PAUSE/MOND-STERED SWBOI PLAY SWBOI PLAY SWBOI PLAY SWBOI PLAY SWBOI PLAY SWBOI SWBO FL+ 2 SEG10 SEG11 SEG12 SEG13 SEG14 SEG15 SEG16 V0L301 SW303 TIMER HT502(2006.09.11) EBY33541501

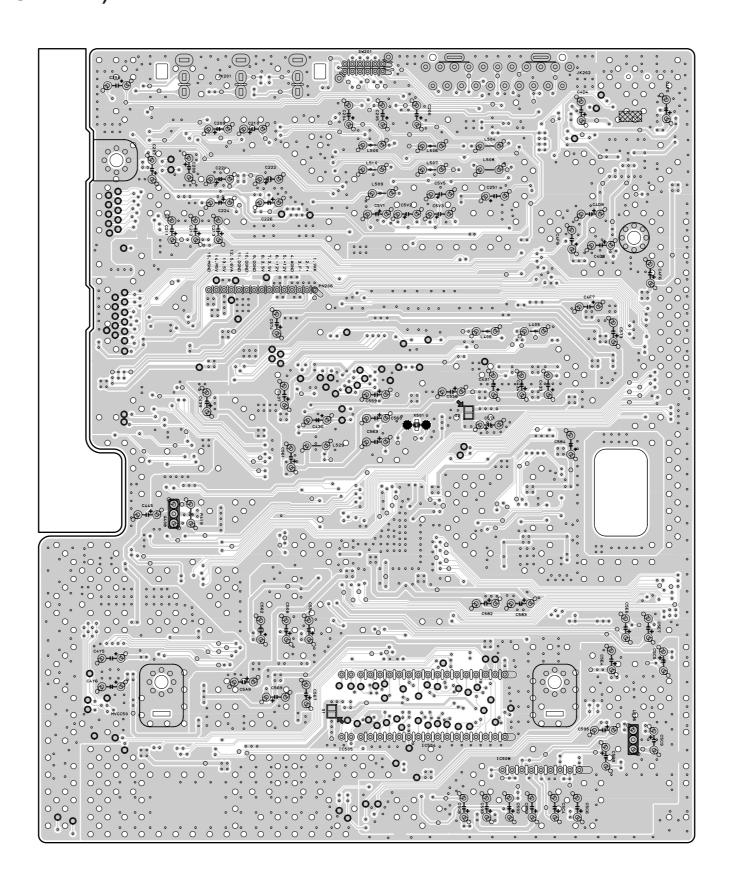
#### 9. HDMI CIRCUIT DIAGRAM +3.3V\_PLL MAX VOLTAGE NOISE : 100mVpp(MAX) **↔**+3.3V C4F8 + C4F9 220/6.34 + C4F9 0.1uF Designers should include decoupling and bypass cap at each power pin in the layout. Transmitter chip should be placed as closely as possible to the HDMI connector. +3.3V +1.80 The impedance of between the each TMDS line and ground must be 50-ohm. Traces should have 100 ohm differential impedance for each differential pair. Place 1000pF and 0-1uF cap close to each PVCC pin The differential lines should be routed as directly as possible from transmitter to connector. +3.3V\_PLL Each TMDS Pair lines have a same line distance. ESD Protection & EMI Filter should be close to HDMI Connector VIAs are no permitted in TMDS lines. TO MPEG P4403 HDMI HM10 □ ACN2012H 0F402 POLK 33WR4F2 IC4D1 HNB D ACM2012H CF403 ES7120 Place 1000pF and 0. fuF cap close to each PVCC pin 13 CEC - 14 RESERVE - 15 S^\* HN3 D Pull down indicates I2C address 0x72 and 0x7A Pull UP indicates I2C address 0x76 and 0x7E 0. fuF C4D4 © 10uF/16v HP\_DET < +3,3V\_PLL IC4D3 uPA672T(XX) LEVEL SHIFTER HMPOF VSYNC TO INTERFACE HDMI HT902/502(2006.09.02) EBY32678801(#5)

# PRINTED CIRCUIT BOARD DIAGRAMS

1. MAIN P.C. BOARD DIAGRAM (TOP VIEW)



# 2. MAIN P.C. BOARD DIAGRAM ( BOTTOM VIEW )



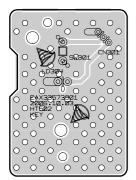
2-28 2-29

#### 3. SMPS P.C. BOARD

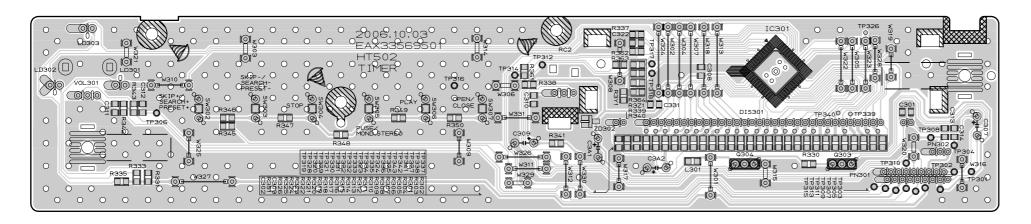
NOTES) Marning
Parts that are shaded are critical
with respect to risk of fire or
electricial shock. HT502 EAX32630901 230\*156 2006.10.03 T5AL 250V (5A250V) 0 **© (3) (b) (3)** C902  $\bigcirc$ 

2-30

#### 4. KEY P.C. BOARD

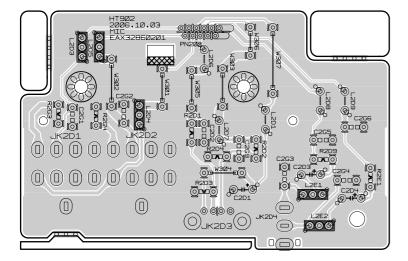


#### 5. TIMER P.C. BOARD



2-32 2-33

## 6. USB P.C. BOARD

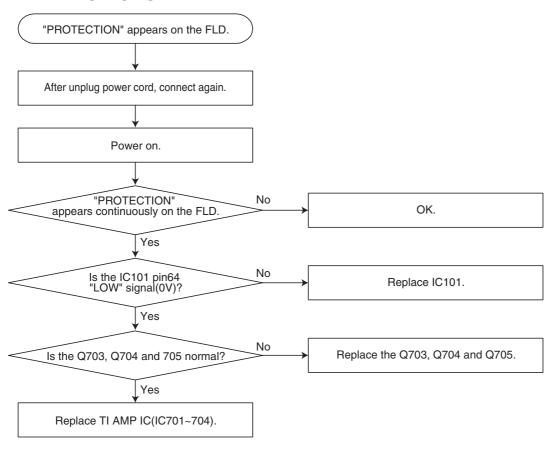


2-35

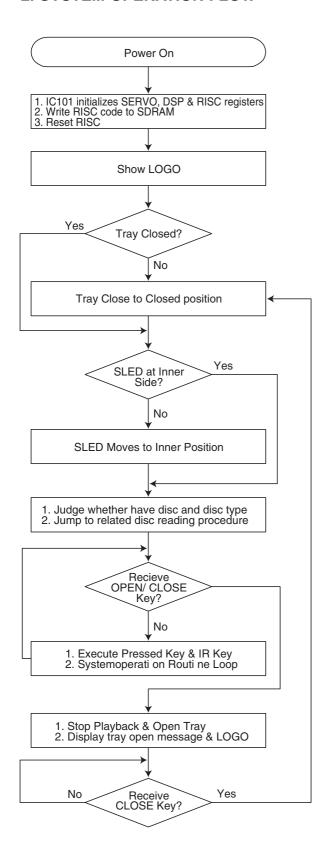
# SECTION 3. DVD & AMP PART

## **ELECTRICAL TROUBLESHOOTING GUIDE**

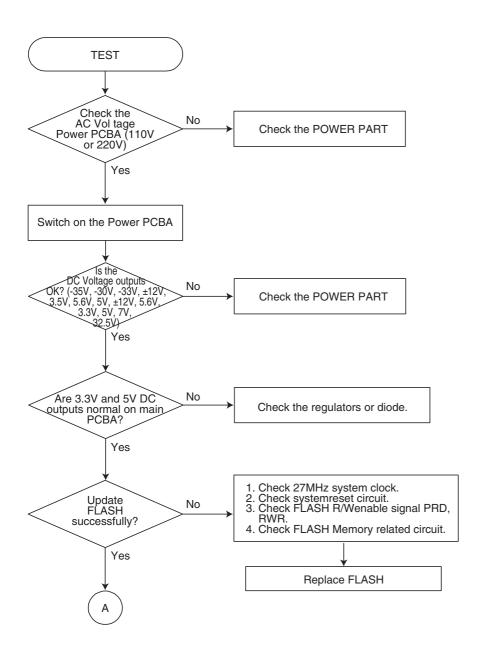
#### 1. AMP PROTECTION

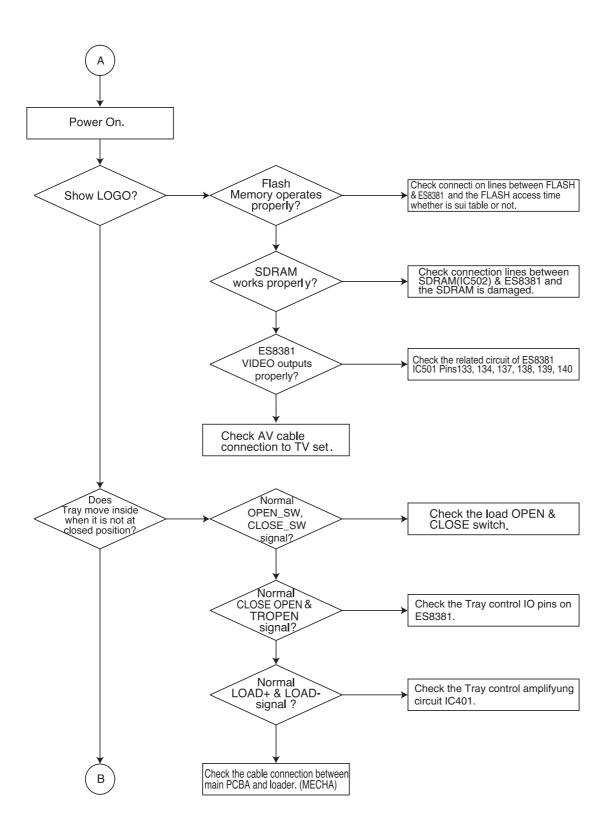


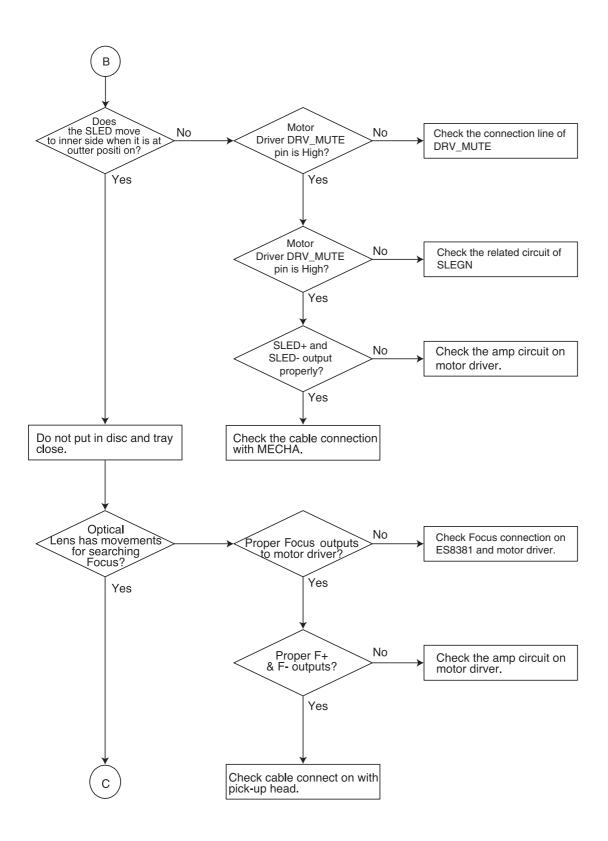
#### 2. SYSTEM OPERATION FLOW

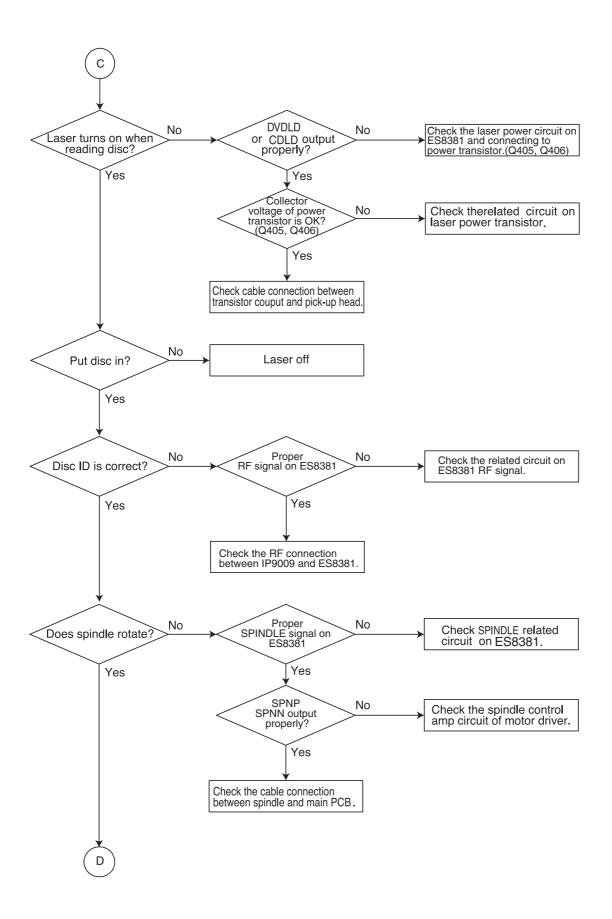


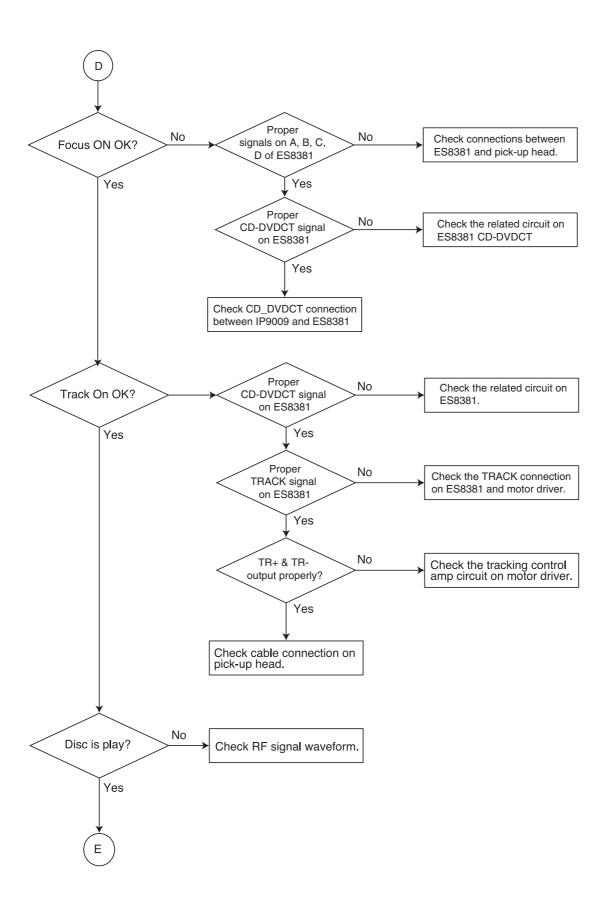
#### 3. TEST & DEBUG FLOW

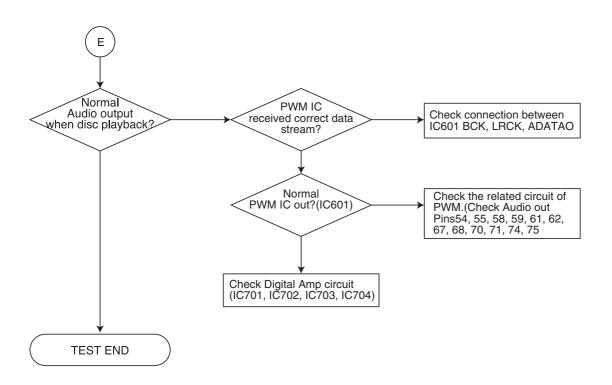




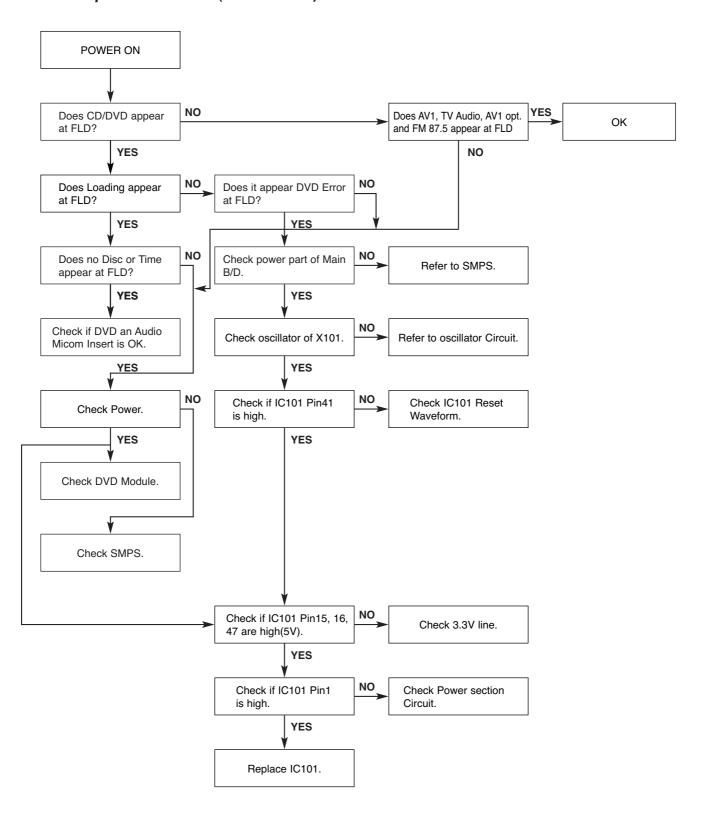








#### 4. AUDIO $\mu$ -COM CIRCUIT(DVD & AMP)



## DETAILS AND WAVEFORMS ON SYSTEM TEST AND DEBUGGING

#### 1. SYSTEM 27MHz CLOCK, RESET, FLASH R/W SIGNAL

#### 1) ES8381 main clock is at 27MHz(X501)

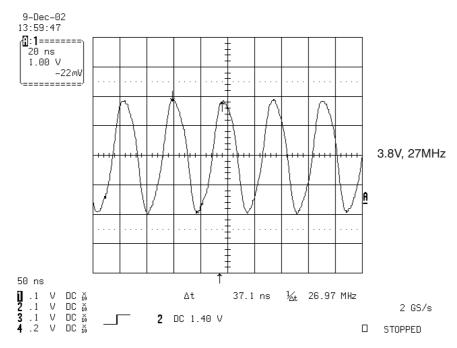


FIG 1-1

### 2) ES8381 reset is high active.

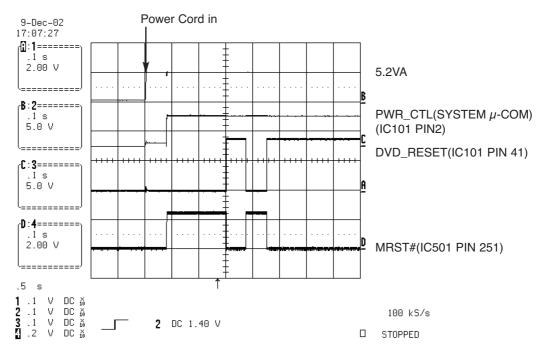


FIG 1-2

#### 3) Flash R/W enable signal during download(Downloading)

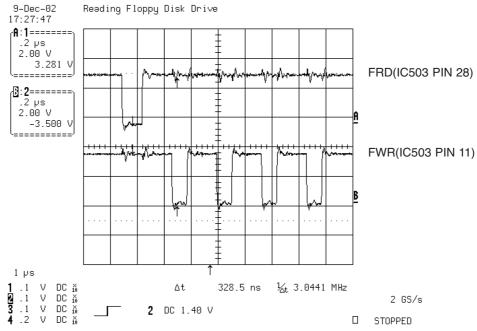
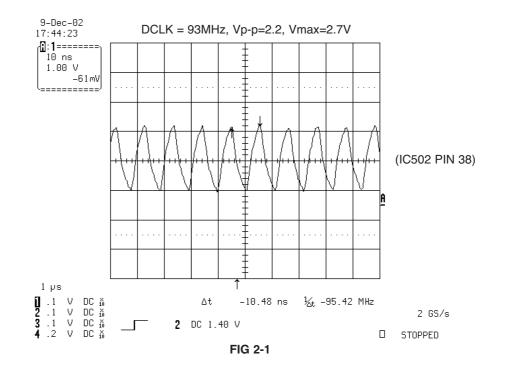


FIG 1-4

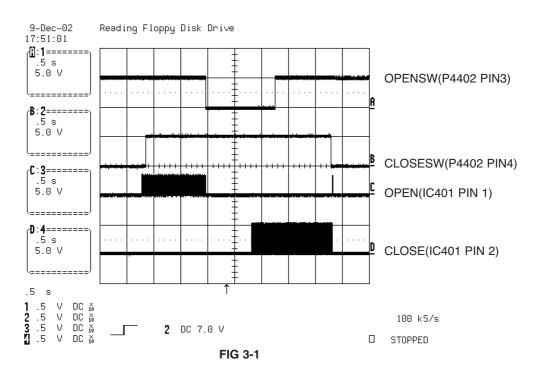
#### 2. SDRAM CLOCK

#### 1) ES8381 main clock is at 27MHz(X501)



#### 3. TRAY OPEN/CLOSE SIGNAL

#### 1) Tray open/close waveform



#### 2) Tray close waveform

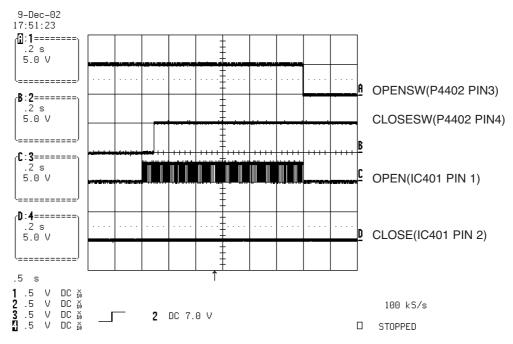


FIG 3-2

#### 3) Tray open waveform

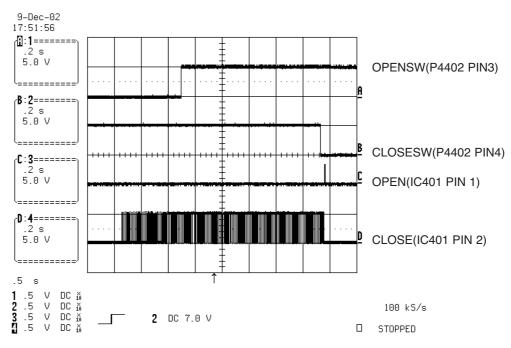


FIG 3-3

#### 4. SLED CONTROL RELATED SIGNAL (NO DISC CONDITION)

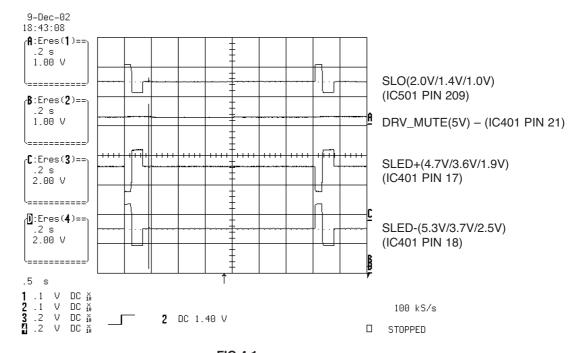


FIG 4-1

#### 5. LENS CONTROL RELATED SIGNAL(NO DISC CONDITION)

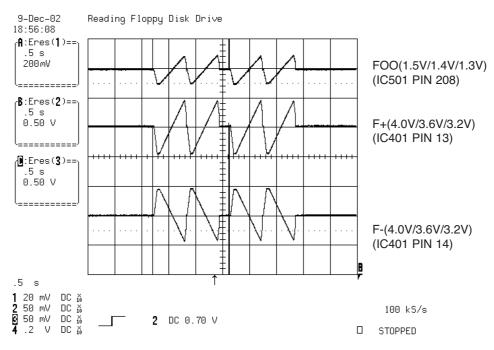


FIG 5-1

#### 6. LASER POWER CONTROL RELATED SIGNAL(NO DISC CONDITION)

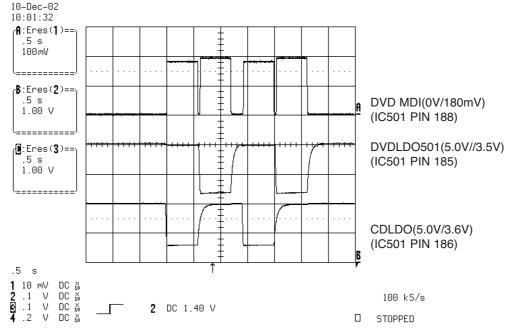


FIG 6-1

#### 7. DISC TYPE JUDGEMENT WAVEFORMS

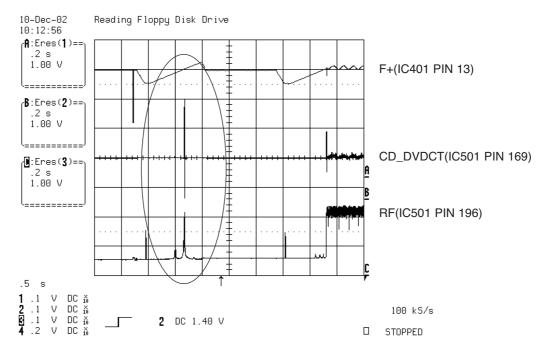


FIG 7-1 (DVD)

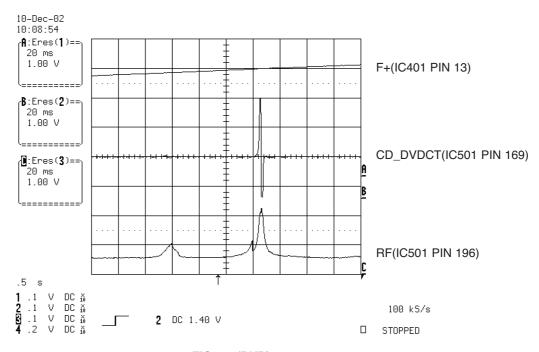


FIG 7-2 (DVD)

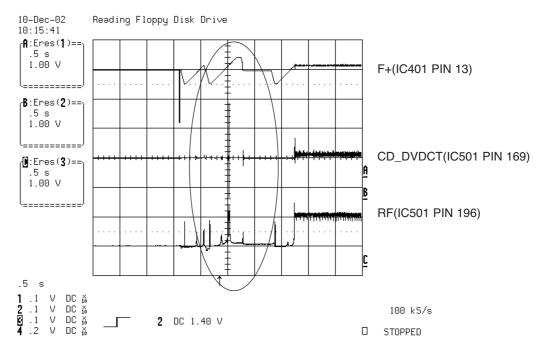


FIG 7-3 (CD)

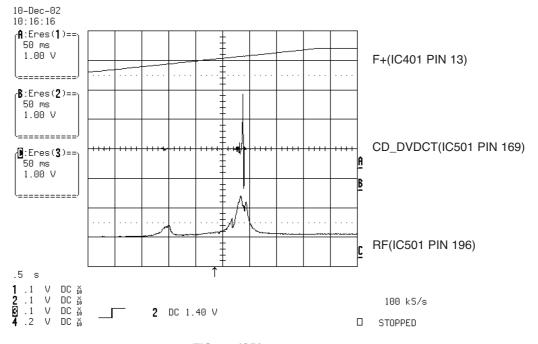


FIG 7-4 (CD)

#### 8. FOCUS ON WAVEFORMS

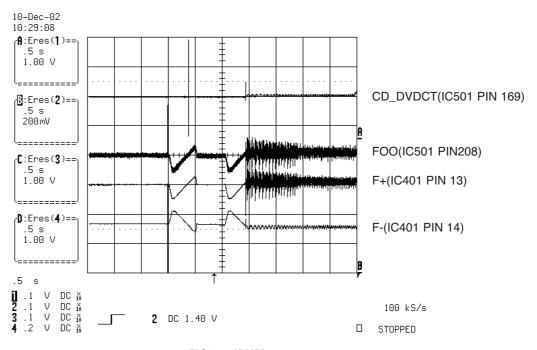


FIG 8-1 (DVD)

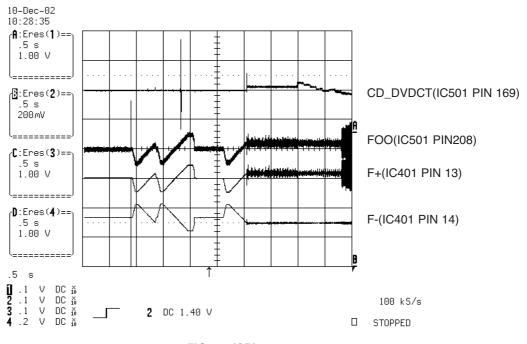


FIG 8-2 (CD)

#### 9. SPINDLE CONTROL WAVEFORMS (NO DISC CONDITION)

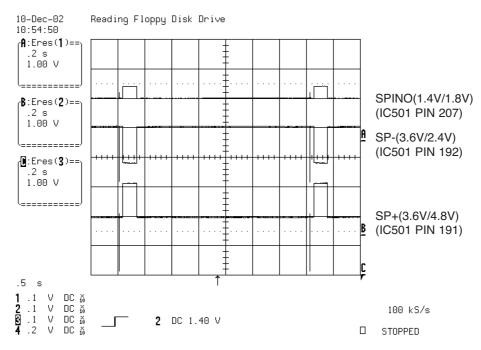


FIG 9-1

#### 10. TRACKING CONTROL RELATED SIGNAL(System checking)

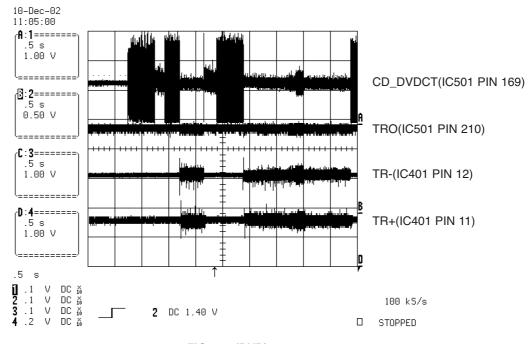


FIG 10-1(DVD)

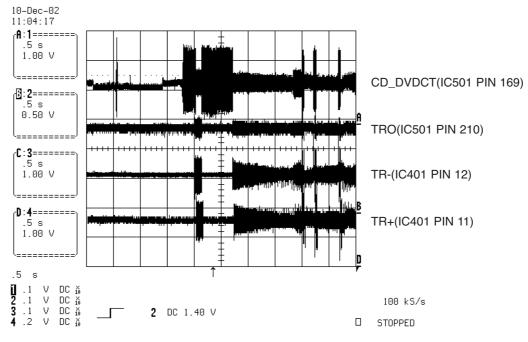


FIG 10-2(CD)

#### 11. ES6698FD VIDEO OUTPUT WAVEFORMS

#### 1) Full colorbar signal(COMPOSIT)

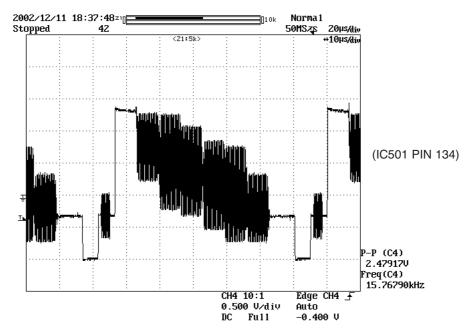
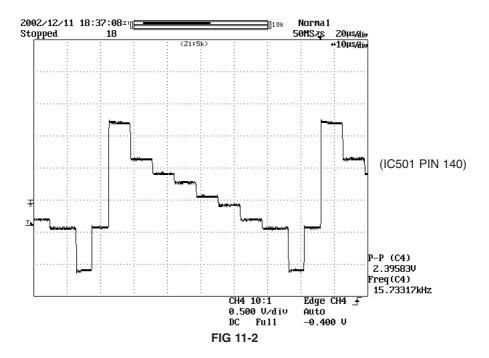


FIG 11-1

## 2) Y



#### 12. AUDIO OUTPUT FROM PWM IC

### 1) Audio L/R

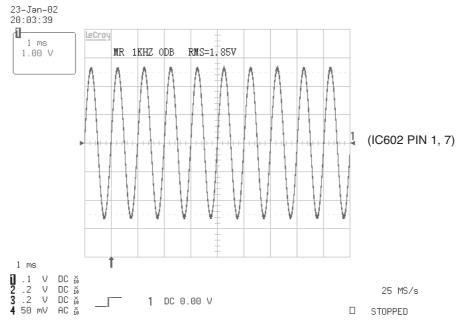


FIG 12-1

## 2) Audio related Signal

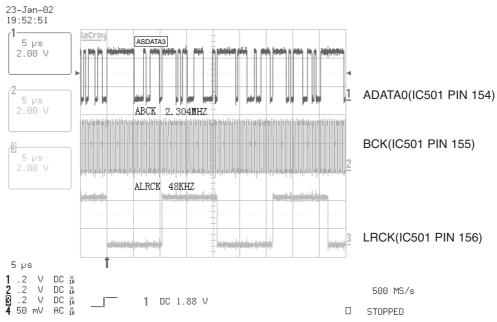
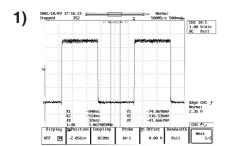
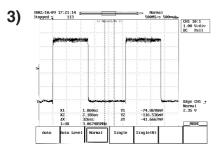


FIG 12-2

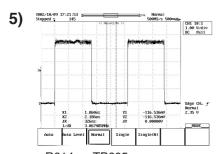
#### 13. DVD & AMP WAVEFORMS



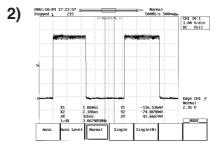
• R620 → TP611 or R621 TP612



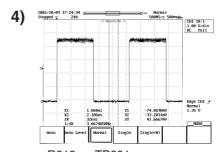
• R612  $\rightarrow$  TP603 or R613 TP604



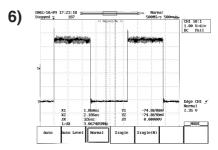
• R614 → TP605 or R615 TP606



• R618 → TP609 or R619 TP610



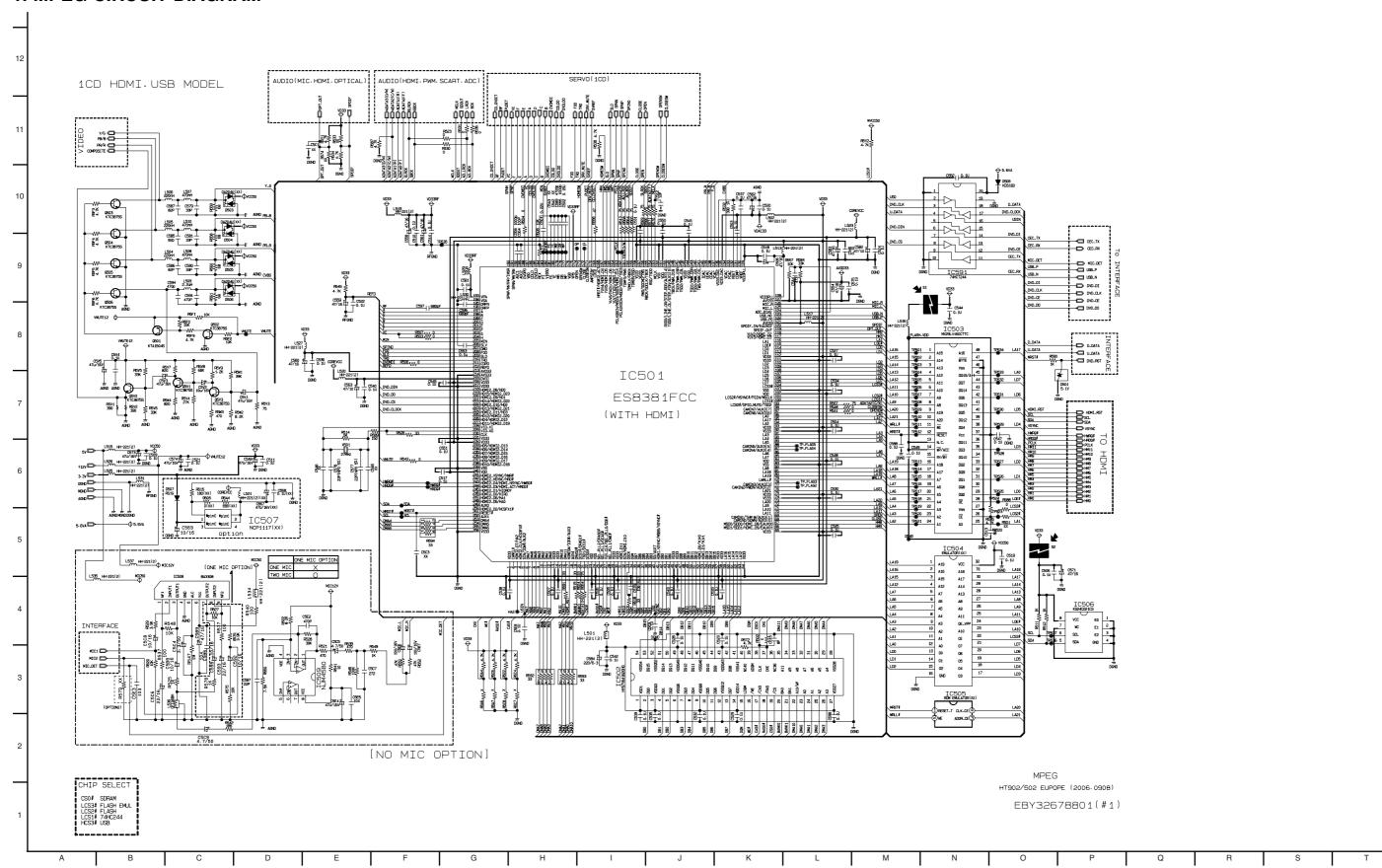
• R610 → TP601 or R611 TP602



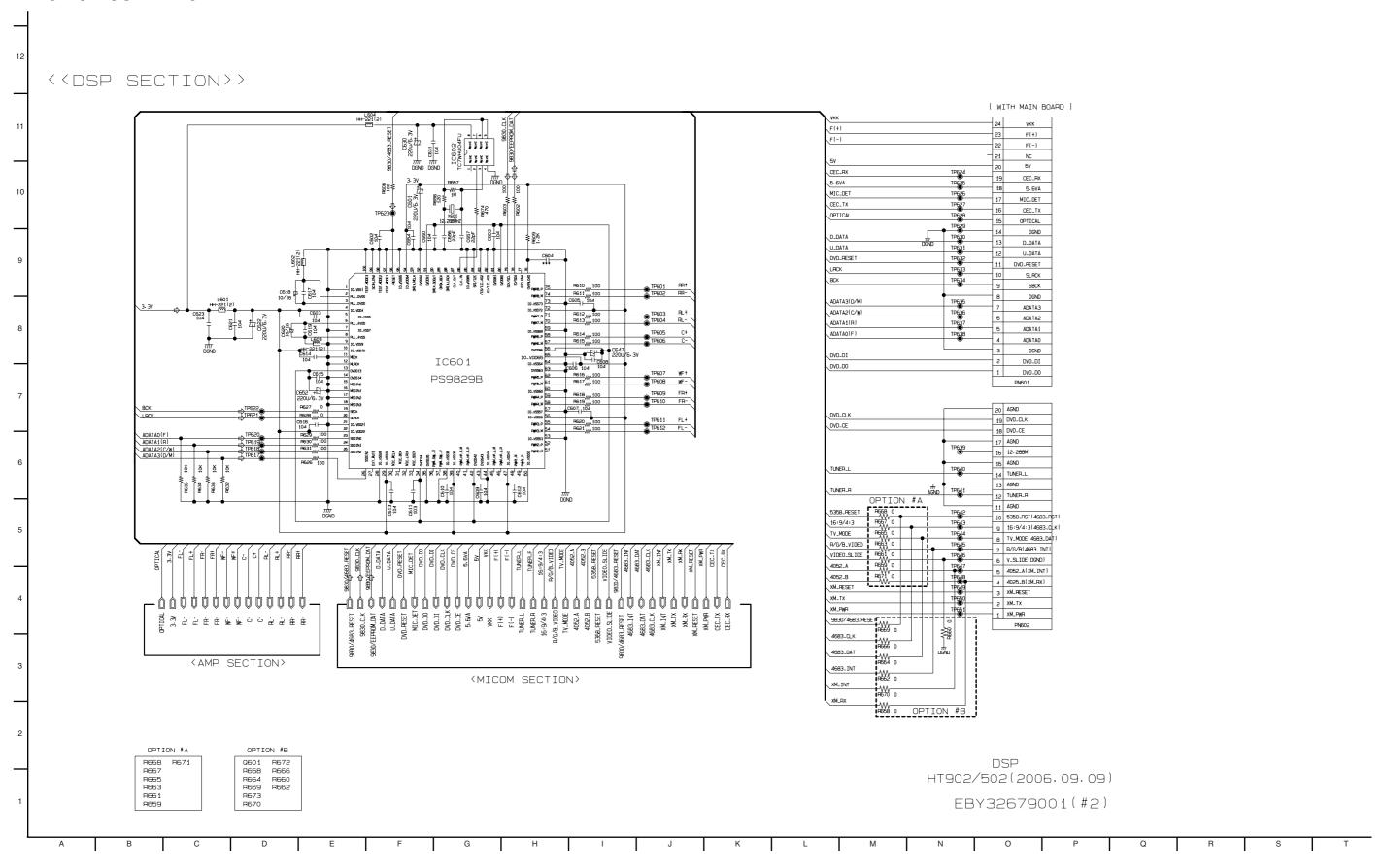
• R616 → TP607 or R617 TP608

## **DVD & AMP CIRCUIT DIAGRAMS**

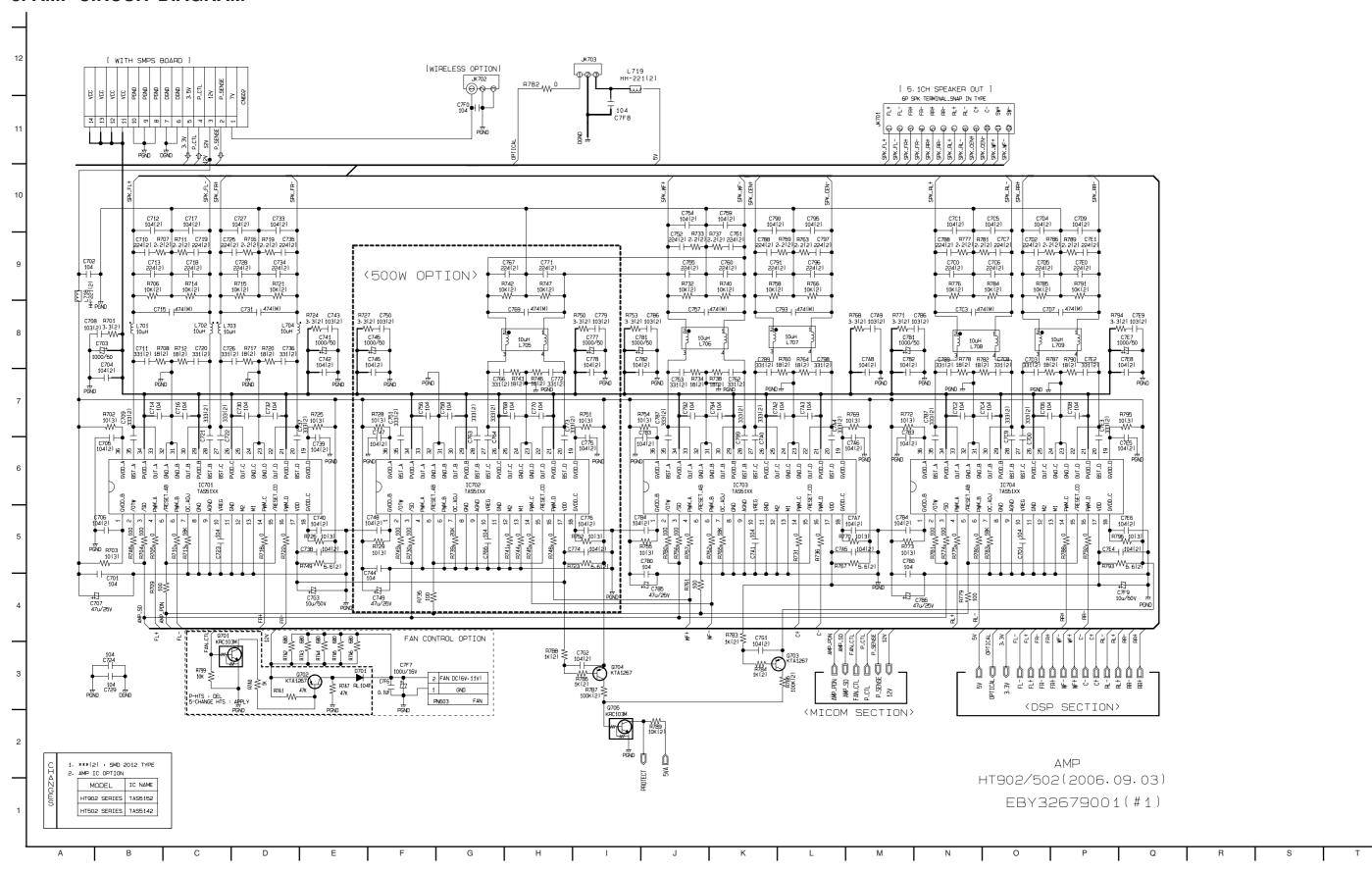
## 1. MPEG CIRCUIT DIAGRAM



#### 2. DSP CIRCUIT DIAGRAM

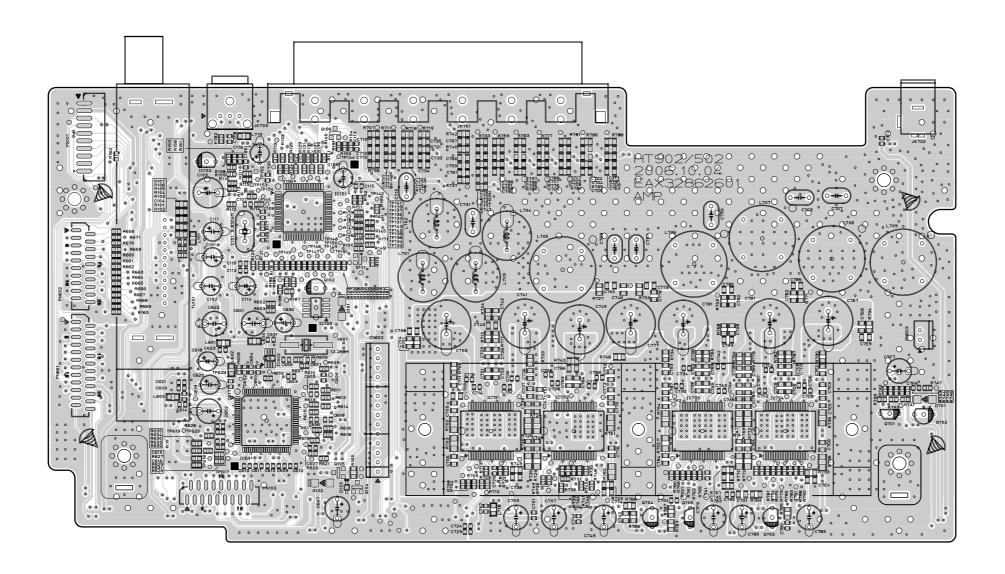


#### 3. AMP CIRCUIT DIAGRAM

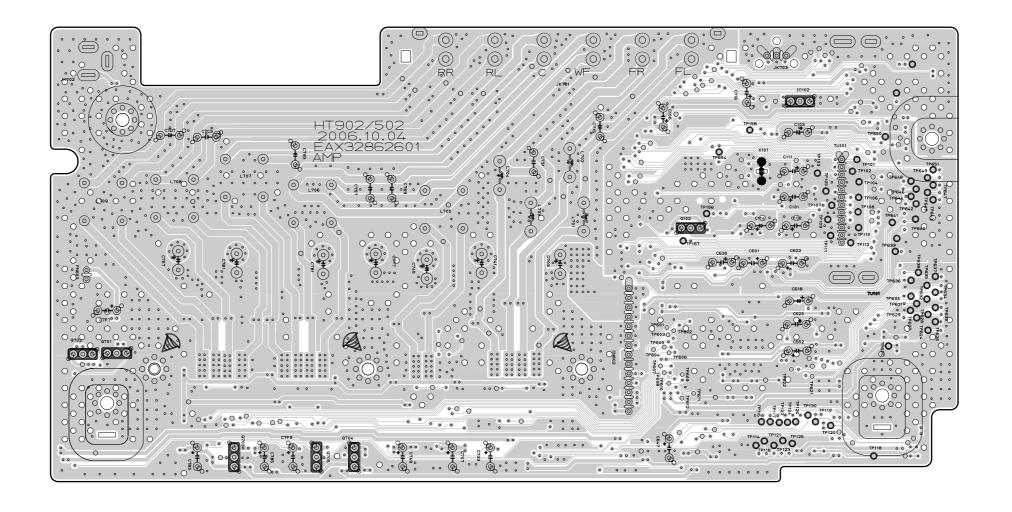


# PRINTED CIRCUIT BOARD DIAGRAMS

1. AMP P.C. BOARD DIAGRAM\_TOP VIEW



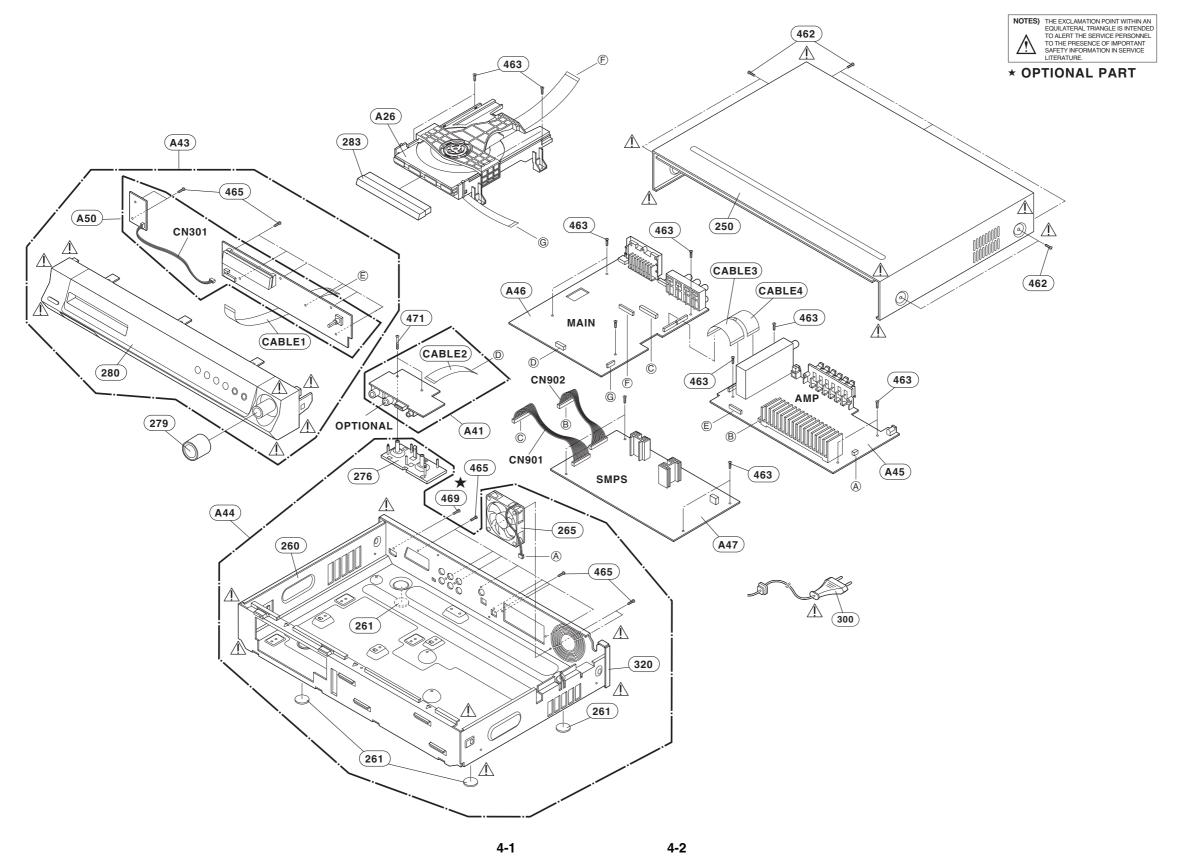
# 2. AMP P.C. BOARD DIAGRAM\_BOTTOM VIEW



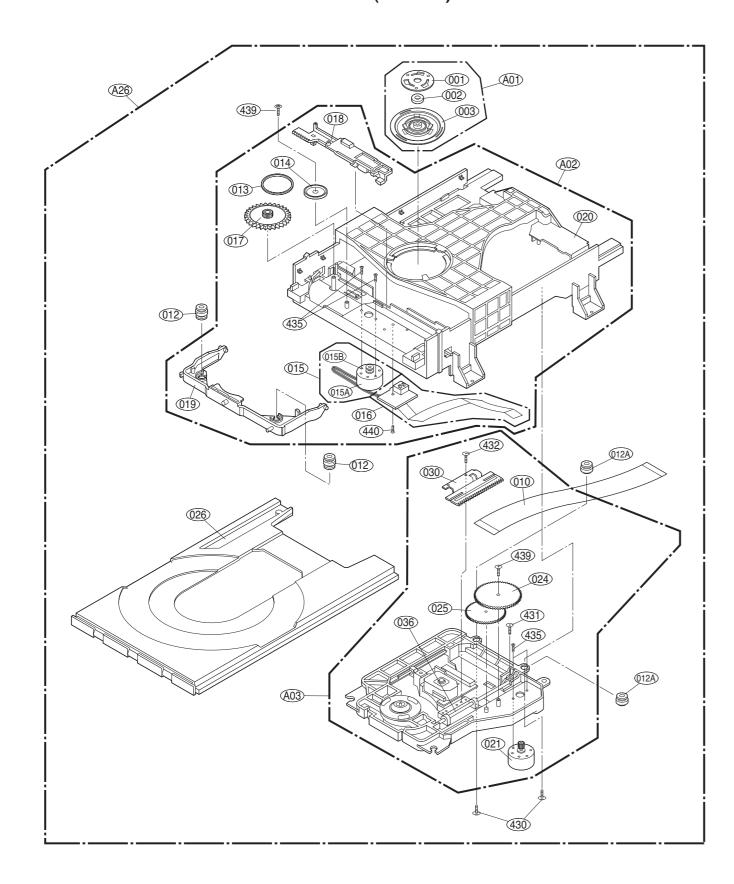
3-31

# **SECTION 4. EXPLODED VIEWS**

## • CABINET AND MAIN FRAME SECTION\_HT502's

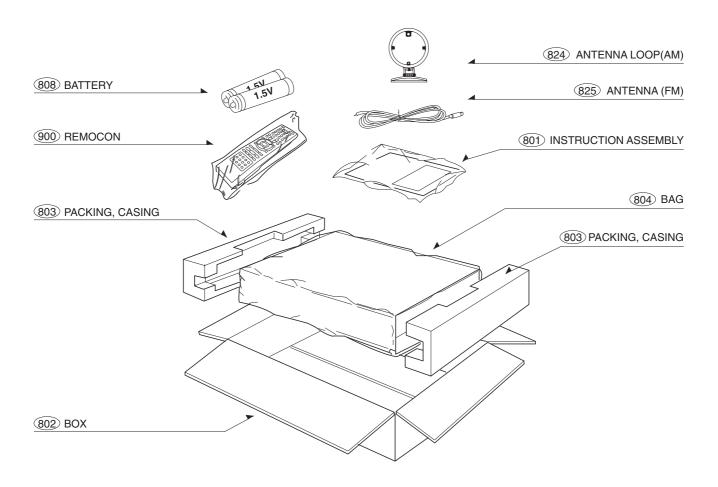


# • DECK MECHANISM EXPLODED VIEW(DP-10A)



MEMO MEMO

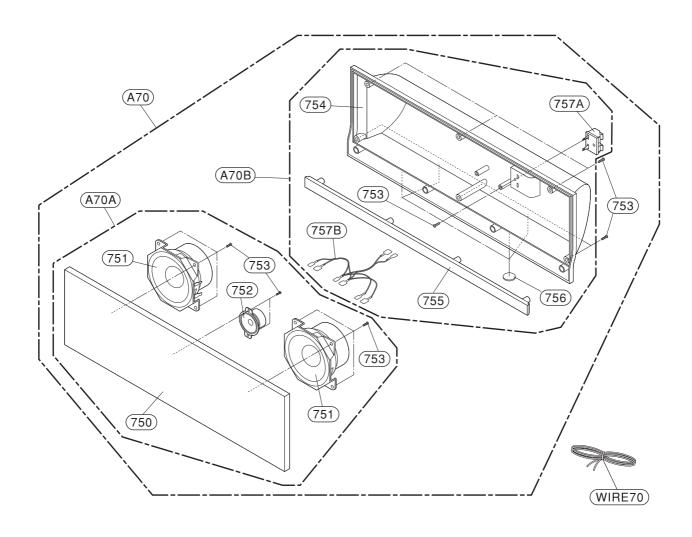
# PACKING ACCESSORY SECTION



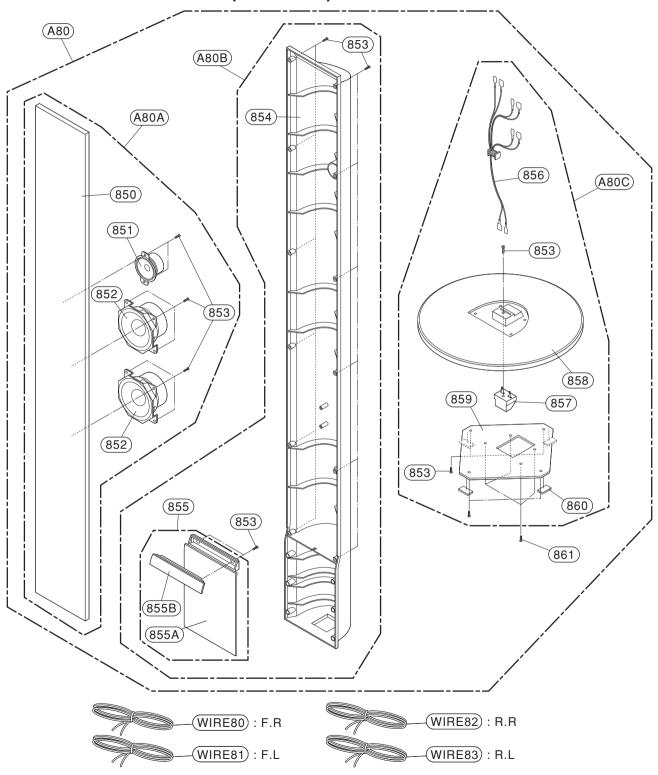
# **MEMO**

# **SECTION 5. SPEAKER SECTION**

# • CENTER SPEAKER(SH52TH-C)



# • FRONT/REAR SPEAKER(SH52TH-S)



# • PASSIVE SUBWOOFER SPEAKER(SH52TH-W)

